

Amendments to the Specification

Please replace the paragraph on page 23, lines 1-28, as previously amended in Amendment After Final Rejection filed October 16, 2009, with the following amended paragraph:

Fig. 9 shows a further embodiment of a magnet assembly at the target resulting in an asymmetrically unbalanced magnet field pattern. This assembly has a first looping magnet subarrangement 87_o of one polarity and having a radius-like extension 87_{o1} . The second magnet subarrangement 87_i is provided distant from and along the outer magnet subarrangement 87_o . These two magnet subarrangements do generate on one hand the magnetron field pattern F_M and the asymmetrically unbalanced field pattern with an area P of maximum flux as shown in fig. 9. The locus of zero field component of the magnetron field pattern F_M defines for the locus L' as was already shown in Figs. 1 and 2, thereby confining the outer area A_o with respect to the inner area A_i . Thereby, at the right-hand side of the arrangement of Fig. 9 the ~~an~~ outer, third magnet subarrangement 87_o87_s projects crescent shaped towards the respective edge of the target arrangement shown at 88. The A projecting area A_Δ of magnet subarrangement 87_o87_s causes the asymmetry of the unbalanced magnetic field. Only at that area A_Δ the magnetron field pattern F_M does not emanate from the target surface which is limited at line 88. This area A_Δ is not more than 12% of the target surface area. When performing the method according to the present invention, i.e. operating the magnetron source and magnetron chamber, especially for sputter-coating the following further settings are preferred:

The plasma is preferably fed with a power in the range of 0.1 to 60 kW, thereby even more preferred within a range of 1 to 40 kW.